



# Product Change Notification

**Change Notification #:** 116527 - 00  
**Change Title:** Intel® Compute Module HNS2600BPBLC24  
Intel® Compute Module HNS2600BPBLC,  
PCN 116527-00, Product Design,  
BMC/FRUSDR Firmware Update in Factory  
and Mechanical Improvements in Power  
Docking Board  
**Date of Publication:** October 04, 2018

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

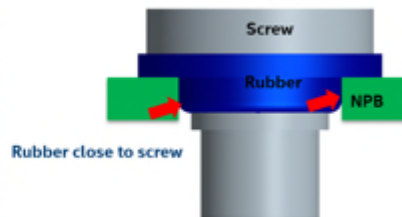
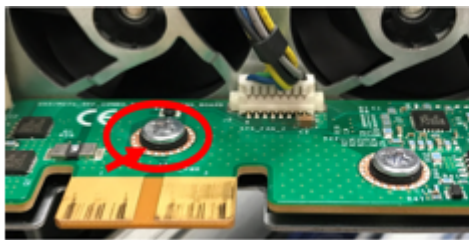
<b>Date Customer Must be Ready to Receive Post-Conversion Material *:</b>	Effective Immediately
---------------------------------------------------------------------------	-----------------------

\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

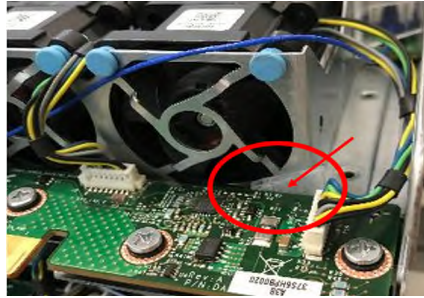
## Description of Change to the Customer:

Intel is implementing the following Improvements on the Intel® Compute Modules HNS2600BPBLC24 and HNS2600BPBLC:

1. BMC Factory Firmware Update to version 1.43g
2. FRUSDR Factory Firmware Update to version 1.36
3. Rubber collar addition to allow more floating for Power Docking Board on left-right direction for a better connection



4. Addition of Plastic Filler between Power Docking Board and Fan Cage to decrease the Power Docking Board Rotation when compute node is inserted



### Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at <http://www.intel.com/support>.

### Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
HNS2600BPBLC	961401	J77062-001	J64353-550	J77062-002	J64353-551
HNS2600BPBLC24	977207	J94709-001	J64353-550	J94709-002	J64353-551

### PCN Revision History:

**Date of Revision:**  
October 4, 2018

**Revision Number:**  
00

**Reason:**  
Originally Published PCN



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## 116527 - 00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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